## **Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of the claims in the application:

## **Listing of Claims:**

## **CLAIMS**

- (Currently Amended) A polish pad comprising:
  a base layer; and
  an ion exchange layer contiguously disposed in the base layer; and
  a base support layer, wherein at least one of the base layer and the base support the ion
  exchange layer is patterned.
- 2. (Original) The polish pad of claim 1, wherein the ion exchange layer comprises ion exchange resin beads.
- (Currently Amended) The polish pad of claim 1, wherein the ion exchange layer emprise comprises ground ion exchange resin beads.
- 4. (Previously Presented) The polish pad of claim 2, wherein the ion exchange beads are embedded in the ion exchange layer.
- 5. (Previously Presented) The polish pad of claim 3, wherein the ground ion exchange beads are embedded in the ion exchange layer.
- 6.-9. (Canceled)
- 10. (Original) The polish pad of claim 1, wherein the ion exchange layer binds cations.
- 11. (Original) The polish pad of claim 10, wherein the ion exchange layer binds copper cations.
- 12. (Currently Amended) An ion exchange polish pad, comprising: eomprising a base layer; and

a <u>contiguous</u> resin layer <u>coupled to the base layer and</u> having ion exchange material embedded therein, wherein at least one of the base layer and the resin layer is patterned.

- 13. (Original) The ion exchange polish pad of claim 12, wherein the ion exchange material is ion exchange resin beads.
- 14. (Original) The ion exchange polish pad of claim 12, wherein the ion exchange material is ion exchange resin powder.
- 15-32 (Canceled)